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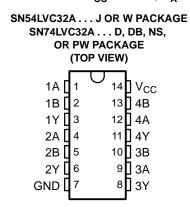
### SN54LVC32A, SN74LVC32A QUADRUPLE 2-INPUT POSITIVE-OR GATES

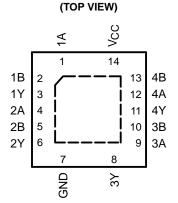
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#### **FEATURES**

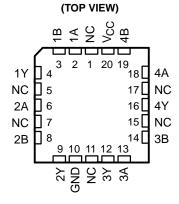
- Operate From 1.65 V to 3.6 V
- Specified From -40°C to 85°C,
  -40°C to 125°C, and -55°C to 125°C
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 3.8 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C

- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  >2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)





SN74LVC32A . . . RGY PACKAGE



SN54LVC32A . . . FK PACKAGE

NC - No internal connection

#### **DESCRIPTION/ORDERING INFORMATION**

The SN54LVC32A quadruple 2-input positive-OR gate is designed for 2.7-V to 3.6-V  $V_{CC}$  operation, and the SN74LVC32A quadruple 2-input positive-OR gate is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The 'LVC32A devices perform the Boolean function Y = A + B or  $Y = \overline{A} \cdot \overline{B}$  in positive logic.

#### **ORDERING INFORMATION**

T <sub>A</sub>			ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Reel of 1000	SN74LVC32ARGYR	LC32A
		Tube of 50	SN74LVC32AD	
4000 / 40500	SOIC - D	Reel of 2500	SN74LVC32ADR	LVC32A
		Reel of 250	SN74LVC32ADT	
	SOP - NS	Reel of 2000	SN74LVC32ANSR	LVC32A
-40°C to 125°C	SSOP - DB	Reel of 2000	SN74LVC32ADBR	LC32A
		Tube of 90	SN74LVC32APW	
	TSSOP - PW	Reel of 2000	SN74LVC32APWR	LC32A
		Reel of 250	SN74LVC32APWT	
	CDIP – J	Tube of 25	SNJ54LVC32AJ	SNJ54LVC32AJ
-55°C to 125°C	CFP – W	Tube of 150	SNJ54LVC32AW	SNJ54LVC32AW
	LCCC - FK	Tube of 55	SNJ54LVC32AFK	SNJ54LVC32AFK

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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### **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

# FUNCTION TABLE (EACH GATE)

INP	UTS	OUTPUT
Α	В	Y
Н	Х	Н
Х	Н	Н
L	L	L

### LOGIC DIAGRAM, EACH GATE (POSITIVE LOGIC)



### Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage range		-0.5	6.5	V	
VI	Input voltage range <sup>(2)</sup>		-0.5	6.5	V	
Vo	Output voltage range <sup>(2)(3)</sup>		-0.5	V <sub>CC</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA	
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA	
Io	Continuous output current			±50	mA	
	Continuous current through V <sub>CC</sub> or GND			±100	mA	
		D package <sup>(4)</sup>		86		
		DB package <sup>(4)</sup>		96		
$\theta_{JA}$	Package thermal impedance	NS package <sup>(4)</sup>		76	°C/W	
		PW package <sup>(4)</sup>		113		
		RGY package <sup>(5)</sup>	47			
T <sub>stg</sub>	Storage temperature range		-65	150	°C	
P <sub>tot</sub>	Power dissipation	$T_A = -40^{\circ}\text{C to } 125^{\circ}\text{C}^{(6)(7)}$		500	mW	

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> The value of  $V_{CC}$  is provided in the recommended operating conditions table.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>(5)</sup> The package thermal impedance is calculated in accordance with JESD 51-5.

<sup>(6)</sup> For the D package: above 70°C, the value of Ptot derates linearly with 8 mW/K.

<sup>(7)</sup> For the DB, DGV, NS, and PW packages: above 60°C, the value of P<sub>tot</sub> derates linearly with 5.5 mW/K.



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## Recommended Operating Conditions<sup>(1)</sup>

			SN54LV	SN54LVC32A -55 TO 125°C	
			−55 TO		
			MIN	MAX	
V	Supply voltage	Operating	2	3.6	V
V <sub>CC</sub>		Data retention only	1.5		V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2		V
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	V
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V <sub>CC</sub>	V
	High level autout august	V <sub>CC</sub> = 2.7 V		-12	A
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 3 V		-24	mA
	Lavidaval avtavt avmant	V <sub>CC</sub> = 2.7 V		12	A
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V		24	mA
Δt/Δν	Input transition rise or fall rate	·		7	ns/V

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### Recommended Operating Conditions<sup>(1)</sup>

					SN74L	VC32A			
			T <sub>A</sub> = 25	T <sub>A</sub> = 25°C		-40 TO 85°C		125°C	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
1/	Supply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V
$V_{CC}$		Data retention only	1.5		1.5		1.5		V
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		0.65 × V <sub>CC</sub>		0.65 × V <sub>CC</sub>		
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		1.7		1.7		V
		V <sub>CC</sub> = 2.7 V to 3.6 V	2		2		2		
	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	(	0.35 × V <sub>CC</sub>		0.35 × V <sub>CC</sub>		0.35 × V <sub>CC</sub>	
$V_{IL}$		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7		0.7		0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8		0.8		0.8	
$V_{I}$	Input voltage		0	5.5	0	5.5	0	5.5	V
Vo	Output voltage		0	$V_{CC}$	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-4		-4		-4	
	High-level output	$V_{CC} = 2.3 \text{ V}$		-8		-8		-8	mA
I <sub>OH</sub>	current	$V_{CC} = 2.7 \text{ V}$		-12		-12		-12	IIIA
		$V_{CC} = 3 V$		-24		-24		-24	
		V <sub>CC</sub> = 1.65 V		4		4		4	
	Low-level output	$V_{CC} = 2.3 \text{ V}$	8 8			8			
I <sub>OL</sub>	current	V <sub>CC</sub> = 2.7 V		12		12		12	
		V <sub>CC</sub> = 3 V		24		24		24	
Δt/Δν	Input transition rise	e or fall rate		7		7		7	ns/V

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

### SN54LVC32A, SN74LVC32A QUADRUPLE 2-INPUT POSITIVE-OR GATES

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### **Electrical Characteristics**

over operating free-air temperature range (unless otherwise noted)

			SN54LVC32A		
PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	–55 TO 125°C	UNIT	
			MIN MAX		
	$I_{OH} = -100 \mu A$	2.7 V to 3.6 V	V <sub>CC</sub> - 0.2		
V	L = 12 mA	2.7 V	2.2	V	
$V_{OH}$	$I_{OH} = -12 \text{ mA}$	3 V	2.4	V	
	$I_{OH} = -24 \text{ mA}$	3 V	2.2		
	I <sub>OL</sub> = 100 μA	2.7 V to 3.6 V	0.2		
$V_{OL}$	I <sub>OL</sub> = 12 mA	2.7 V	0.4	V	
	I <sub>OL</sub> = 24 mA	3 V	0.55		
I <sub>I</sub>	$V_I = 5.5 \text{ V or GND}$	3.6 V	±5	μΑ	
I <sub>cc</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	10	μΑ	
$\Delta I_{CC}$	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V	500	μΑ	

### **Electrical Characteristics**

over operating free-air temperature range (unless otherwise noted)

			SN74LVC32A							
PARAMETER	TEST CONDITIONS	$v_{cc}$	T <sub>A</sub>	$T_A = 25^{\circ}C$			35°C	–40 TO 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
	$I_{OH} = -100  \mu A$	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V <sub>CC</sub> - 0.2		V <sub>CC</sub> - 0.3		
	I <sub>OH</sub> = -4 mA	1.65 V	1.29			1.2		1.05		
\/	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			1.7		1.55		V
V <sub>OH</sub>	1 - 12 mA	2.7 V	2.2			2.2		2.05		v
	$I_{OH} = -12 \text{ mA}$	3 V	2.4			2.4		2.25		
	$I_{OH} = -24 \text{ mA}$	3 V	2.3			2.2		2		
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.1		0.2		0.3	
	I <sub>OL</sub> = 4 mA	1.65 V			0.24		0.45		0.6	
V <sub>OL</sub>	$I_{OL} = 8 \text{ mA}$	2.3 V			0.3		0.7		0.85	V
	I <sub>OL</sub> = 12 mA	2.7 V			0.4		0.4		0.6	
	I <sub>OL</sub> = 24 mA	3 V			0.55		0.55		8.0	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	3.6 V			±1		±5		±20	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			1		10		40	μΑ
Δl <sub>CC</sub>	One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND	2.7 V to 3.6 V			500		500		5000	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.3 V		5						pF

### **Switching Characteristics**

over operating free-air temperature range (unless otherwise noted) (see Figure 1)

					SN54LV	C32A	
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	−55 TO 125°C		UNIT	
		( 5.7)	(33.1.3.1)		MIN	MAX	
	4	A or B	V	2.7 V		4.4	20
	<sup>L</sup> pd	AUIB	T	3.3 V ± 0.3 V	1	3.8	ns





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### **Switching Characteristics**

over operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER						SN	74LVC32	2A			
	FROM (INPUT)	_	V <sub>cc</sub>	T <sub>A</sub> = 25°C			-40 TO 85°C		-40 TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
		A or B Y	1.8 V ± 0.15 V	1	4.2	8.2	1	8.7	1	10.2	
	A 0" D		2.5 V ± 0.2 V	1	2.6	4.9	1	5.4	1	6.9	
t <sub>pd</sub>	AUB		2.7 V	1	3	4.2	1	4.4	1	5.5	ns
			3.3 V ± 0.3 V	1	2.5	3.6	1	3.8	1	5	
t <sub>sk(o)</sub>			3.3 V ± 0.3 V					1		1.5	ns

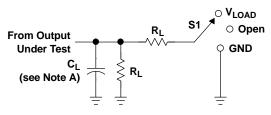
### **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

	PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	TYP	UNIT
		f = 10 MHz	1.8 V	7.5	pF
C <sub>pd</sub>	Power dissipation capacitance per gate		2.5 V	10.6	
			3.3 V	12.5	



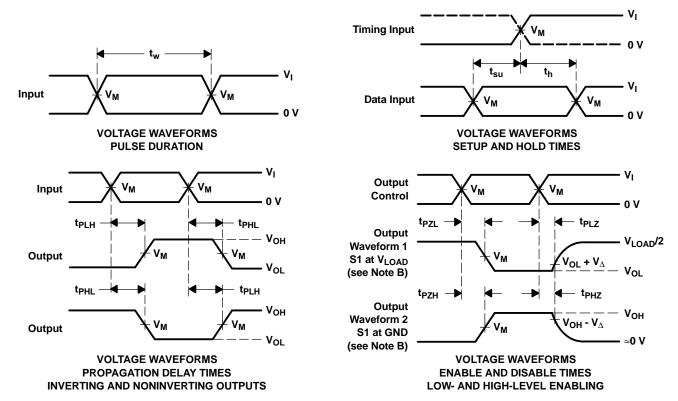
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	$V_{LOAD}$
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

**LOAD CIRCUIT** 

.,	INPUTS		.,	.,		_	.,
V <sub>CC</sub>	V <sub>I</sub>	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$oldsymbol{V}_\Delta$
1.8 V $\pm$ 0.15 V	v <sub>cc</sub>	≤ <b>2</b> ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤ <b>2</b> ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



### **PACKAGING INFORMATION**

	Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5	5962-9761801Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5	5962-9761801QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5	5962-9761801QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
	SN74LVC32AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LVC32ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
5	SN74LVC32ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LVC32ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
\$	SN74LVC32ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LVC32ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LVC32ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LVC32ADT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	SN74LVC32ADTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
5	SN74LVC32ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LVC32ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LVC32ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
,	SN74LVC32APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LVC32APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LVC32APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LVC32APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
S	SN74LVC32APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
12	N74LVC32APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN	N74LVC32APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
5	SN74LVC32APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LVC32APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
12	N74LVC32APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LVC32ARGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
;	SNJ54LVC32AFK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC



#### PACKAGE OPTION ADDENDUM

26-Sep-2005

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins F	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SNJ54LVC32AJ	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LVC32AW	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## W (R-GDFP-F14)

### CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



#### FK (S-CQCC-N\*\*)

#### **28 TERMINAL SHOWN**

#### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



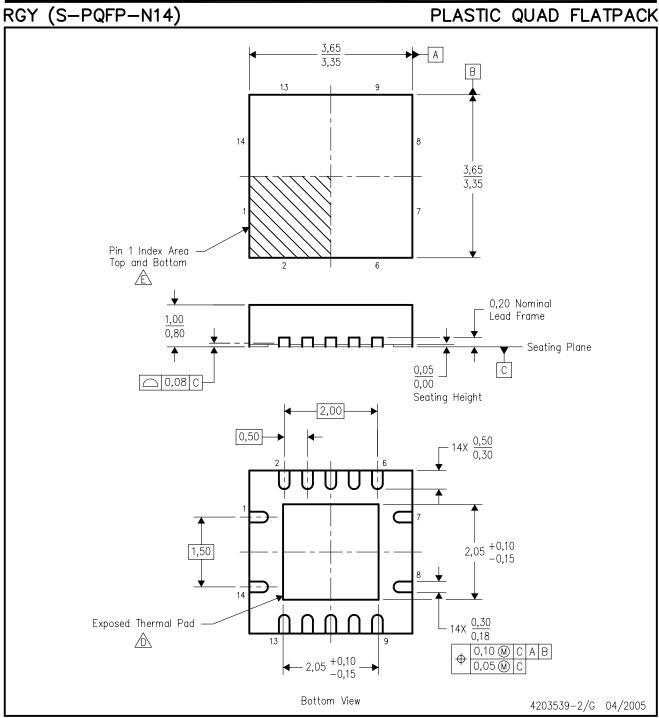
## D (R-PDSO-G14)

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.

Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.

F. Package complies to JEDEC MO-241 variation BA.



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



### DB (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

### PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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